

ABSTRACT OF THE DISCLOSURE

A multilayered circuit board has good imbedding properties for circuit patterns, and an interlayer insulating material having superior adhesive force and interlayer insulating properties. In a multilayered circuit board wherein interlayer connection is achieved by the contact of minute pointed protrusions, provided on a first conductive circuit layer, with a second conductive circuit layer, interlayer insulation is achieved by a film having a three-layer structure, comprising a thermoplastic film inserted between a pair of thermosetting adhesive layers.